

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)			
30	0.010 at V _{GS} = 10 V	30	26.5 nC			
30	0.018 at V _{GS} = 4.5 V	25	20.5 110			

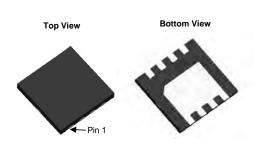
FEATURES

- · Halogen-free
- TrenchFET® Power MOSFET
- 100 % R_g and UIS Tested

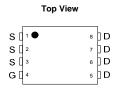


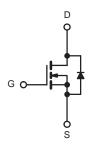
APPLICATIONS

- DC/DC Conversion
 - Low-Side Switch
- Notebook PC
- Gaming



DFN 3x3 EP





N-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 20	v	
	T _C = 25 °C		30		
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 70 °C	I _D	22.6		
Continuous Diam Current (1) = 150 °C)	T _A = 25 °C] 'b [21.5 ^{b, c}		
	T _A = 70 °C	1 -	17.1 ^{b, c}	Α Α	
Pulsed Drain Current		I _{DM}	100		
Continuous Source-Drain Diode Current	T _C = 25 °C	1.	13		
Continuous Source-Diam Diode Current	T _A = 25 °C	ls –	3.1 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	10		
Avalanche Energy	L = 0.1 mH		5	mJ	
	T _C = 25 °C		16.7		
Maximum Power Dissipation	T _C = 70 °C	P _D	10.7	W	
Maximum Fower Dissipation	T _A = 25 °C] 'D [3.7 ^{b, c}	VV	
	T _A = 70 °C		2.4 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R_{thJA}	27	34	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	6	7.5		

Notes

- a. Based on $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. Maximum under Steady State conditions is 85 °C/W.



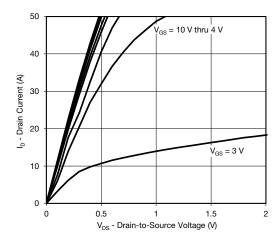
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	/T _J		27		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 5.6		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1.0		3.0	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			10	10 µA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α
	В	V _{GS} = 10 V, I _D = 15 A		0.010		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		0.018		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A		75		S
Dynamic ^b				L		ı
Input Capacitance	C _{iss}			650		pF
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		236		
Reverse Transfer Capacitance	C _{rss}			20		
Total Gate Charge		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 10 A		10	10 20	nC
				4.5	9	
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		2.1		
Gate-Drain Charge	Q_{gd}]		0.7		
Gate Resistance	R _g	f = 1 MHz	0.2	1.1	2.2	Ω
Turn-On Delay Time	t _{d(on)}			8	16	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		16	30	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		17	35	
Fall Time	t _f]		7	15	
Turn-On Delay Time	t _{d(on)}			14	30	- ns - -
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		50	100	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		16	30	
Fall Time	t _f			8	18	
Drain-Source Body Diode Characteristi	cs					
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			13	
Pulse Diode Forward Current ^a	I _{SM}				100	Α
Body Diode Voltage	V _{SD}	I _S = 3 A			1.2	V
Body Diode Reverse Recovery Time	t _{rr}				40	ns
Body Diode Reverse Recovery Charge	Q _{rr}	1 10 A dl/dt 100 A/::= T 05 00			20	nC
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		12.5		
Reverse Recovery Rise Time	t _b	1		7.5		ns

Notes:

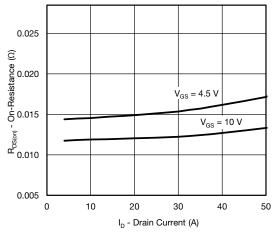
- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

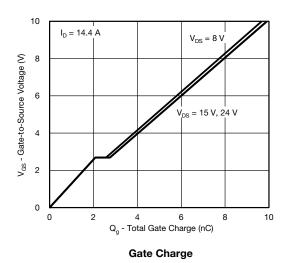


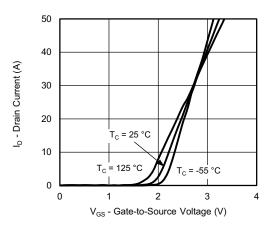


Output Characteristics

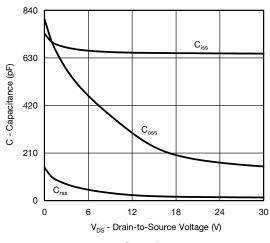


On-Resistance vs. Drain Current

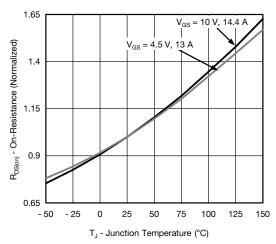




Transfer Characteristics

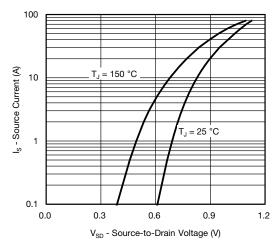


Capacitance

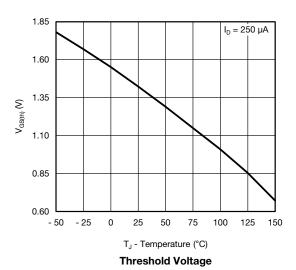


On-Resistance vs. Junction Temperature



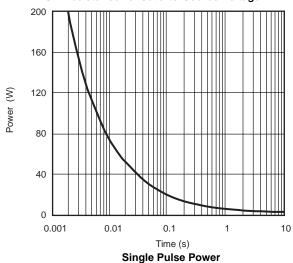


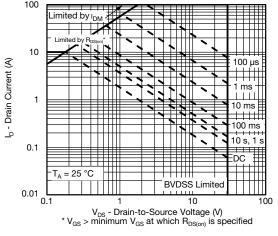
Source-Drain Diode Forward Voltage



 $C_{\text{O}} = 0.025$ $C_{\text{O}} = 0.020$ $C_{\text{O}} = 0.020$ $C_{\text{O}} = 0.015$ $C_{\text{O}} =$

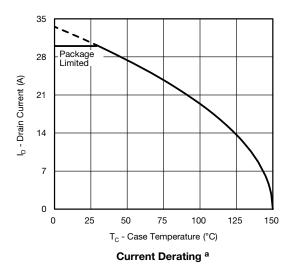
On-Resistance vs. Gate-to-Source Voltage

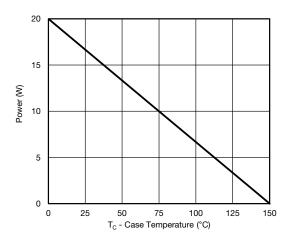




Safe Operating Area, Junction-to-Ambient





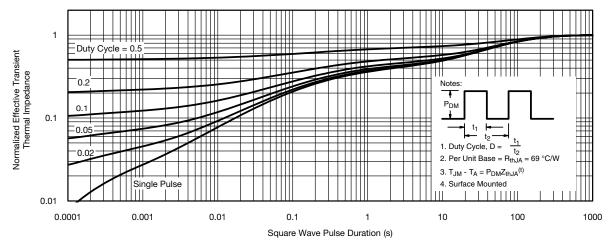


Power, Junction-to-Case

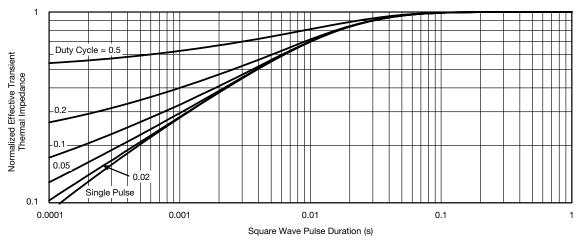
Note

a. The power dissipation P_D is based on T_J max. = 25 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



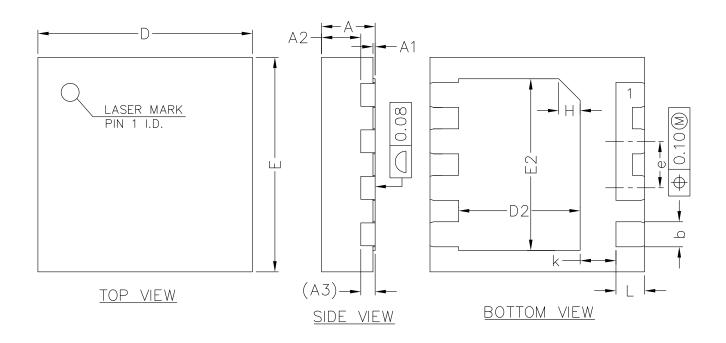


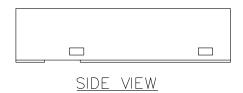
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case







COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX		
Α	0.70	0.75	0.80		
A1	0.00	0.02	0.05		
A2	0.50	0.55	0.60		
А3	0.20REF				
b	0.30	0.35	0.40		
D	2.90	3.00	3.10		
Е	2.90	3.00	3.10		
D2	1.60	1.70	1.80		
E2	2.30	2.40	2.50		
е	0.55	0.65	0.75		
K	0.40	0.50	0.60		
L	0.35	0.40	0.45		



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